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Applicants: Jennifer E. Appleyard et al.

Examiner: Xiuquin Sun

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For: TEMPERATURE COMPENSATION
IN MAXIMUM FREQUENCY
MEASUREMENT AND SPEED SORT

Conf. No.: 2915

Dated: December 13, 2005

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AS
*12/20/05***AMENDMENT AND RESPONSE UNDER 37 C.F.R. §1.116**

Sir:

This document is submitted in response to the Final Office Action mailed October 13, 2005. No new matter has been introduced.

CERTIFICATION OF FACSIMILE TRANSMISSION

I hereby certify that this paper is being facsimile transmitted to the Patent and Trademark Office on the date shown below.

Dated: December 13, 2005
Steven Fischman

4. (Original) The method of claim 3, further including measuring the chip temperature with an on-chip diode.

5. (Previously Presented) The method of claim 4, further including measuring the chip temperature with the on-chip diode by forcing a current through the on-chip diode, measuring the diode voltage at the start of test when the temperature during test T_{dtest} is known, and measuring the diode voltage again after the F_{max} test when the temperature T_{dtest} is unknown, and using the measurements to determine a predicted F_{max} at T_{max} , based upon which the part is sorted into speed categories.

6. (Original) The method of claim 1, further including determining a change of the temperature sensitive parameter of the chip that is the chip power consumption.

7. (Original) The method of claim 1, further including determining a change of the temperature sensitive parameter of the chip that is the chip I (input)/O (output) timings.

8. (Original) The method of claim 1, further including determining maximum and minimum voltage tests which measure the highest and lowest possible voltages at which a product will operate.

9. (Currently Amended) The method of claim 1, wherein further including testing the chip further comprises testing the chip in preproduction tests to provide a realistic indication of speed